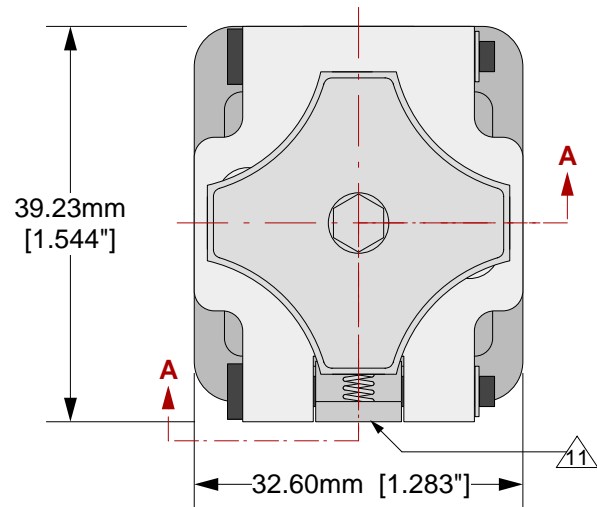
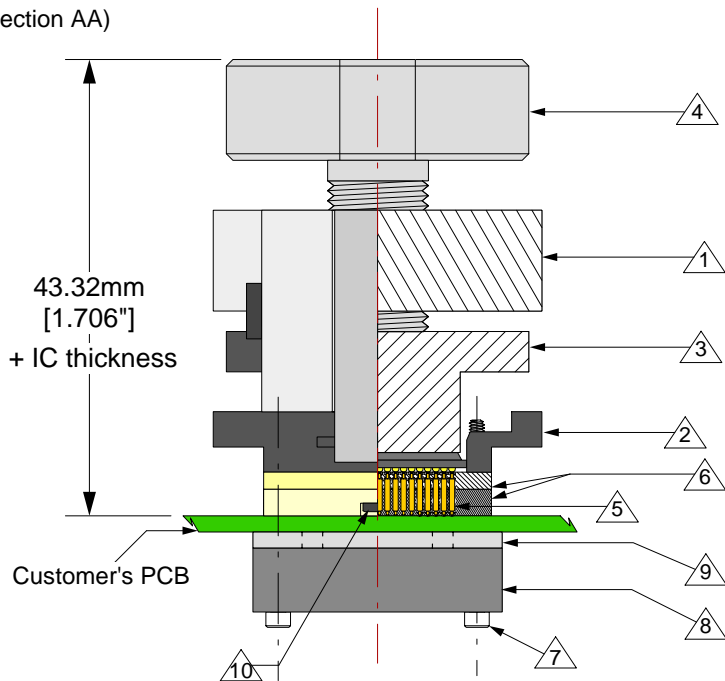


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

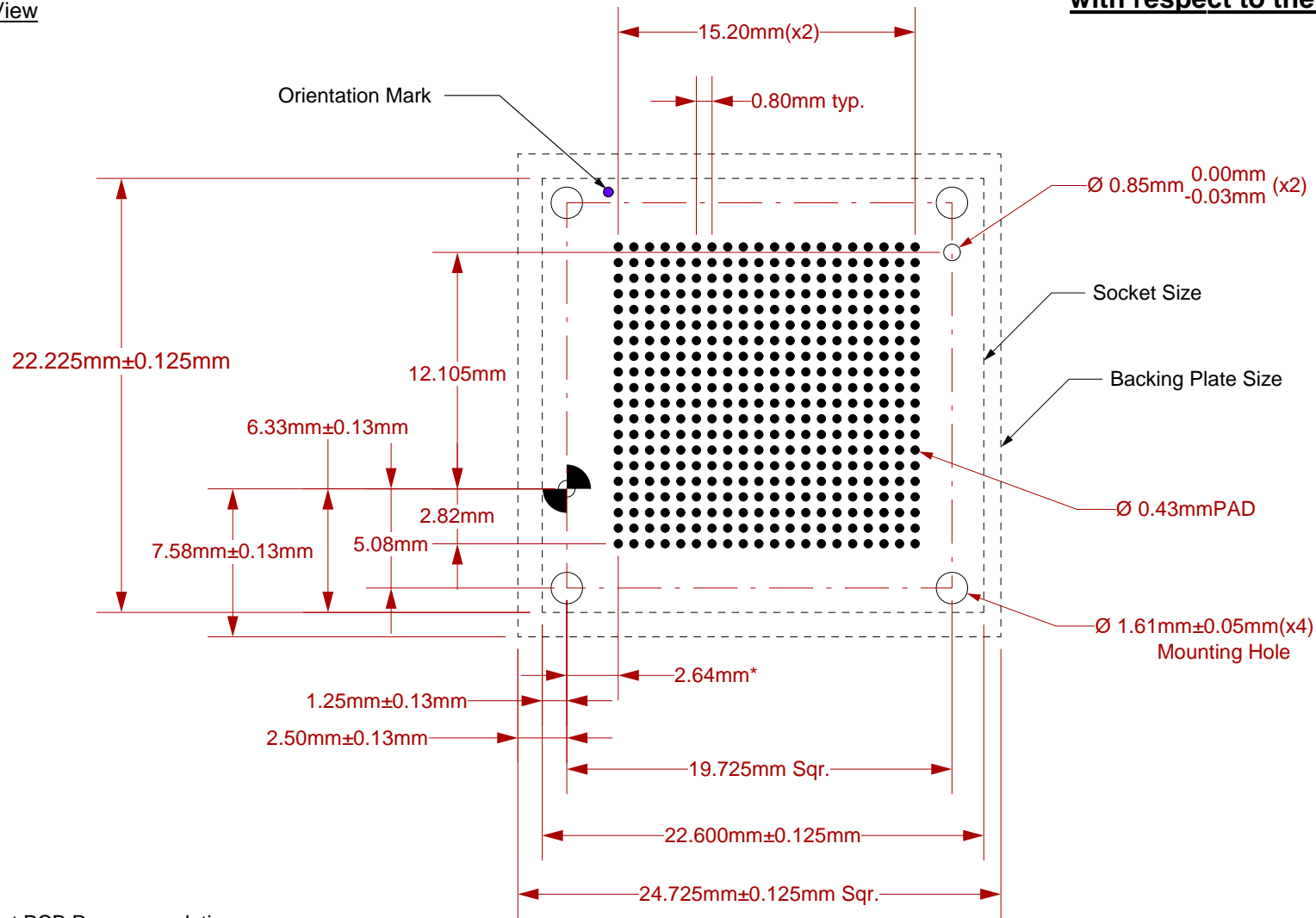
- ① Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- ② Socket Base: Black anodized Aluminum. Height = 6 mm.
- ③ Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- ④ Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- ⑤ Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- ⑥ Pogo Pin Guides: Ultem 1000.
- ⑦ Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- ⑧ Backing Plate: Black anodized Aluminum
- ⑨ Insulation Plate: FR4/G10
- ⑩ Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- ⑪ Latch: Black anodized Aluminum.

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	SS-BGA400H-01 Drawing		Status: Released	Scale: 1.25:1	Rev: A
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com		Drawing: H. Hansen	Date: 6/22/05	
			File: SS-BGA400H-01 Dwg	Modified:	

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

Total thickness: 1.5mm min.
Plating: Gold or Solder finish

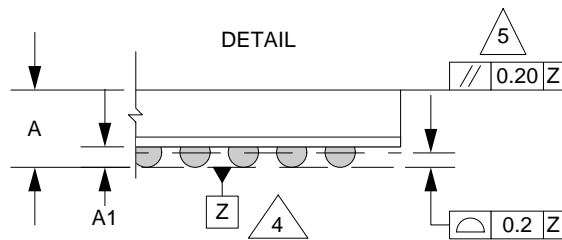
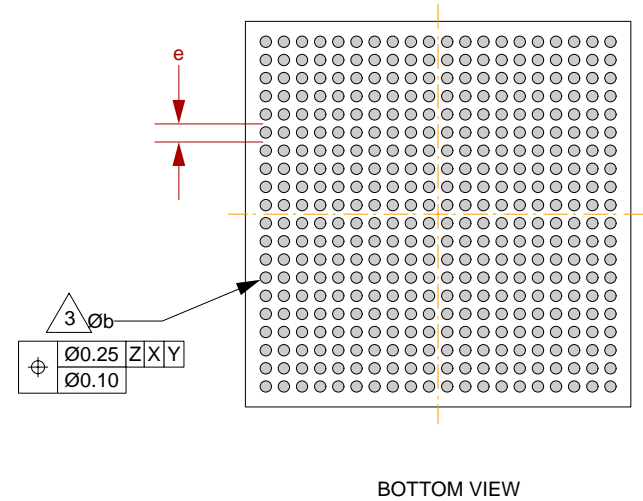
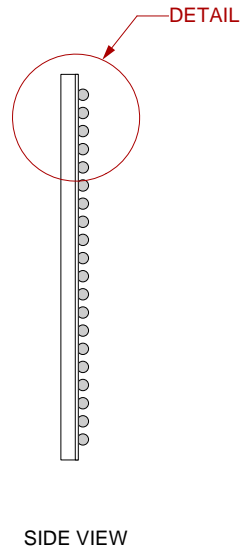
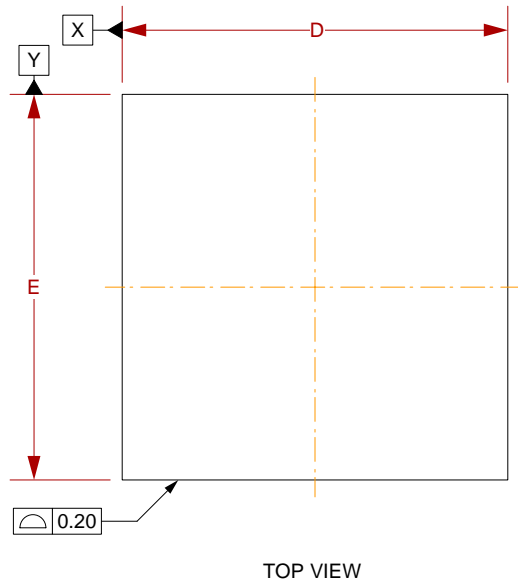


DXF DATA WILL BE PROVIDED

	SS-BGA400H-01 Drawing	Status: Released	Scale: 3:1	Rev: A
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 6/22/05
		File: SS-BGA400H-01 Dwg	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

Compatible BGA Spec



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

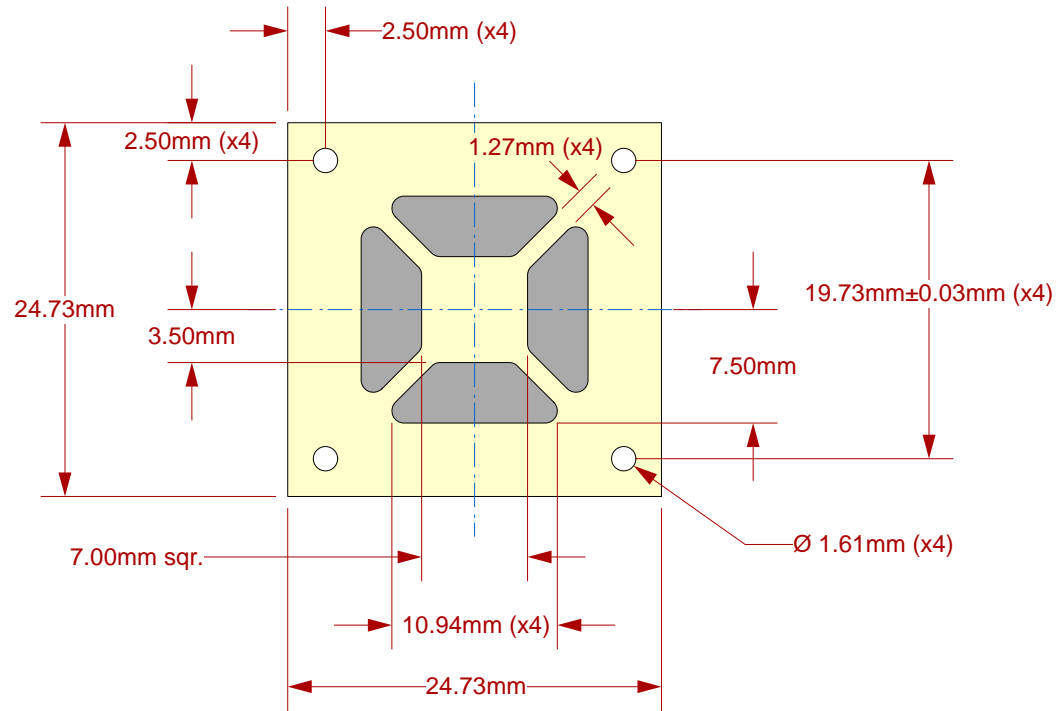
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.2	0.45
b		0.55
D	17.00 BSC	
E	17.00 BSC	
e	0.8 BSC	

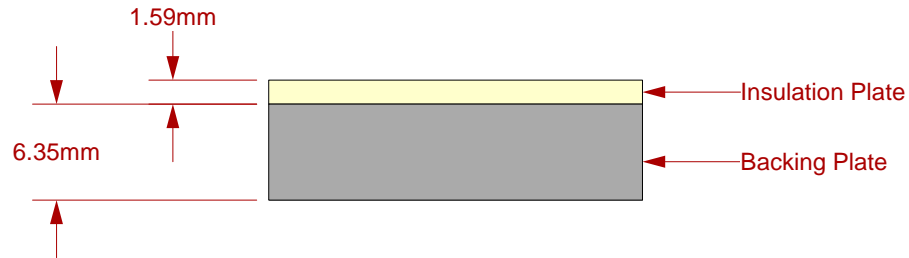
20 x 20 Array

	SS-BGA400H-01 Drawing			Status: Released	Scale:	Rev: A
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com			Drawing: H. Hansen		Date: 6/22/05
				File: SS-BGA400H-01 Dwg		Modified:


Top View



Side View



Description: Backing Plate with Insulation Plate

	SS-BGA400H-01 Drawing	Status: Released	Scale:	Rev: A
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		File: SS-BGA400H-01 Dwg	Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)